

**LISTING OF CLAIMS:**

Claims 1 – 4 (Canceled).

5. (Currently Amended) ~~The equipment according to claim 3, further comprising:~~

Equipment for soldering and bonding a flexible printed circuit board on a printed circuit board, wherein the flexible printed circuit board is made of thermoplastic resin, the equipment comprising:

a heater head for pressing and heating the flexible printed circuit board on the printed circuit board;

a jig for preventing the thermoplastic resin composing the flexible printed circuit board from flowing out in a case where the flexible printed circuit is heated by the heater head; and

an electrode for supplying electricity to the heater head,

wherein the jig and the heater head have a predetermined positional relationship in such a manner that the jig is to be disposed between the flexible printed circuit board and the heater head when the flexible printed circuit board is pressed and heated by the heater head,

wherein the jig includes a thin plate having a base plate and a wing plate,

wherein the base plate is parallel to a top surface of the heater head to be sandwiched between the flexible printed circuit board and the heater head,

wherein the wing plate is disposed on both sides of the base plate to be bent from the base plate,

wherein the printed circuit board is rigid,

wherein the thin plate is made of SUS stainless steel,

wherein the jig further includes a heat sink made of copper,

wherein the wing plate is mounted on the heat sink so that heat of the wing plate is

conducted to the heat sink,

wherein the heater head is mounted on the electrode, and

wherein the jig is movably supported by the electrode through an installation member so that the jig is movable in a direction perpendicular to the base plate.

6. (Original) The equipment according to claim 5,

wherein the heat sink is cooled by an air supplied from an outside fan.

7. (Original) The equipment according to claim 6,

wherein the heat sink includes a notch,

wherein the installation member is made of insulation material, and includes a through hole, and

wherein the air is introduced to the heat sink through the notch and the through hole.

8. (Currently Amended) ~~The equipment according to claim 1, further comprising:~~  
Equipment for soldering and bonding a flexible printed circuit board on a printed circuit board,  
wherein the flexible printed circuit board is made of thermoplastic resin, the equipment  
comprising:

a heater head for pressing and heating the flexible printed circuit board on the printed  
circuit board;

a jig for preventing the thermoplastic resin composing the flexible printed circuit board  
from flowing out in a case where the flexible printed circuit is heated by the heater head; and

a heating stage for preliminarily heating the printed circuit board and for mounting the

printed circuit board,

wherein the heating stage includes a base and an attachment table disposed on the base,  
and

wherein the printed circuit board is mounted on and adhered to the attachment table,  
wherein the jig and the heater head have a predetermined positional relationship in such a manner that the jig is to be disposed between the flexible printed circuit board and the heater head when the flexible printed circuit board is pressed and heated by the heater head,

wherein the jig includes a thin plate having a base plate and a wing plate,  
wherein the base plate is parallel to a top surface of the heater head to be sandwiched between the flexible printed circuit board and the heater head, and

wherein the wing plate is disposed on both sides of the base plate to be bent from the base plate.

Claim 9 (Canceled).

10. (Currently Amended) ~~The equipment according to claim 9,~~  
Equipment for soldering and bonding a flexible printed circuit board on a printed circuit board, wherein the flexible printed circuit board is made of thermoplastic resin, the equipment comprising:

a heater head for pressing and heating the flexible printed circuit board on the printed circuit board; and

a jig for preventing the thermoplastic resin composing the flexible printed circuit board from flowing out in a case where the flexible printed circuit is heated by the heater head,

wherein the jig and the heater head have a predetermined positional relationship in such

a manner that the jig is to be disposed between the flexible printed circuit board and the heater head when the flexible printed circuit board is pressed and heated by the heater head,

wherein the jig includes a thin plate having a base plate and a wing plate,

wherein the base plate is parallel to a top surface of the heater head to be sandwiched between the flexible printed circuit board and the heater head,

wherein the wing plate is disposed on both sides of the base plate to be bent from the base plate,

wherein the heater head is hollow,

wherein the heater head has a top end having a horizontal plate and a pair of vertical plates disposed on both sides of the horizontal plate,

wherein the horizontal plate and the vertical plates have a thickness, which is thinner than other portions,

wherein the top end of the heater head further includes a pair of connection portions disposed on upper ends of the vertical plates, respectively,

wherein the horizontal plate is parallel to the base plate,

wherein the vertical plate is perpendicular to the horizontal plate, and

wherein the connection portions are protruded obliquely and upwardly from both upper ends of the vertical plates so that the connection portions separate away.

11. (Original) The equipment according to claim 10,

wherein the horizontal plate, the vertical plates and the connection portions are capable of generating heat.

Claims 12 – 21 (Withdrawn)